

Task-oriented engineer with robust problem-solving skills and 7+ years of experience in process integration and flawless technology management. Equipped with practical knowledge of semiconductor and advanced packaging industry, manufacturing, yield improvement, and defect analysis. Passionate about self-learning information technology (programming languages/web systems) to heighten work efficiency and accuracy. A fast learner with high adaptability in new fields and a culturally sensitive communicator on account of global exchange and visiting student experience.

EXPERTISE

Languages

English - Full professional proficiency (TOEFL iBT: 112)
Mandarin Chinese - Native

Skills

Information Technology: Visual Studio, WinForms, SQL, ASP.NET, C#, jQuery, HTML, CSS, Bootstrap, VBA
Industry Knowledge: Advanced Packaging, Defect Analysis, Yield Improvement, Technology Management

EXPERIENCE

TSMC

- System Integration Engineer (Apr 2020 - present)

- Used SQL(Oracle)/NoSQL(MongoDB) Database API to develop web applications based on ASP.NET framework for data analysis.
- Developed Windows programs using C#, VBA, and SQL for productivity enhancement.
- Communicated with internal users to define requirements, design/deploy/implement/test system, and continuous improvements.
- Supervised a team of 5 engineering technicians to handle backend customer requests of new product design and satisfied customer special demand.

- Technology Core Team Engineer (Feb 2019 - Apr 2020)

- Defined the 1st process flow auto-creation SOP for TSMC 3DFabric.
- Defined bumping/assembly technology infrastructure for 3D IC roadmap. (Division Stop & Fix Award Winner)
- Handled process change with perfect quality management, considering interactions between technologies and processes.

- Advanced Packaging Process Integration Engineer (Nov 2014 - Feb 2019)

- Developed InFO along with SoC throughout N16/N10/N7/N5 technology. (Suggestion Committee Award Winner)
- Saved expense cost by constructing preserving methodologies of goods. (Division Contribution Award)
- Collaborated with customers on inline issue resolution and yield improvement.

EDUCATION

Linköping University

Exchange Program, Institute of Technology (2013 - 2014)

National Taiwan University

Master of Science in Materials Science and Engineering (2011 - 2013)

Thesis: Interfacial Reactions Between Copper Substrate and Lead-Free Solder for 3D IC Applications

- Session Presenter, TMS 2012 Annual Meeting & Exhibition (Orlando, FL)
- Poster, Material Research Society-Taiwan (MRS-T) (Yunlin, Taiwan)

National Taiwan University

Bachelor of Science in Materials Science and Engineering (2007 - 2011)

- Presidential Award Winner
- Visiting Student, University of Oxford (Oxford, UK)